

## MEDIA ALERT

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## USB-IF to Showcase Emerging SuperSpeed USB Technology at IDF

**WHAT:** At [Intel Developer Forum](#) (IDF), the [USB Implementers Forum](#) (USB-IF) will unveil several never-before-seen SuperSpeed USB technology demonstrations. These include:

- **World's first PC motherboard with SuperSpeed USB.** The [ASUS](#) X58 motherboard includes SuperSpeed USB functionality enabled by the [NEC Electronics](#)  $\mu$ PD720200 host controller. The motherboard will exchange data with a [LucidPort](#) SuperSpeed USB mass storage device running the new USB Attached SCSI Protocol (UASP), which delivers improved performance and reduced latency.
- **World's first notebook computer connecting to a SuperSpeed USB-enabled external solid-state drive.** A [Fujitsu](#) notebook computer with built-in USB 3.0 support enabled by the NEC Electronics  $\mu$ PD720200 host controller will exchange data with an external SuperSpeed USB drive from [Buffalo Technology](#).
- **World's first SuperSpeed USB-enabled digital video camera.** A prototype high performance digital video camera from [Point Grey Research](#), which utilizes a 3 megapixel [Sony](#) IMX036 CMOS image sensor to output 1080p HD images at 60 FPS, will stream uncompressed HD video to a laptop PC through a SuperSpeed USB ExpressCard from [Fresco Logic](#).

The demonstrations will take place during two USB 3.0 technical sessions at IDF. For more information about the technical sessions, please visit the IDF Web site at: <http://www.intel.com/idf/training-sessions/>. The USB-IF will also have a community in the IDF Technology Showcase, featuring several USB-IF member companies. Members of the press and analyst communities are welcome to attend the technical sessions as well as the technology showcase. To schedule an individual press briefing with a USB-IF spokesperson at IDF please e-mail [press@usb.org](mailto:press@usb.org).

**WHEN:** September 22 – 24, 2009

**WHERE:** Intel Developer Forum  
Moscone Center, San Francisco, CA

**WHO:** The [USB Implementers Forum](#)

### About SuperSpeed USB

SuperSpeed USB brings significant performance enhancements to the ubiquitous USB standard, while remaining compatible with the billions of USB enabled devices currently deployed in the market. SuperSpeed USB will deliver 10x the data transfer rate of Hi-Speed USB, as well as improved power efficiency.

The USB 3.0 specification was developed by the USB 3.0 Promoter Group which consists of Intel Corporation, Hewlett-Packard Company, Microsoft Corporation, NEC Corporation, ST-Ericsson and Texas Instruments.

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